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#### What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	25MHz
Connectivity	I <sup>2</sup> C, SPI, UART/USART
Peripherals	DMA, LCD, POR, PWM, WDT
Number of I/O	57
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8.25K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.8V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	76-VFQFN Dual Rows, Exposed Pad
Supplier Device Package	76-DQFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f964-a-gm

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

# C8051F96x

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Figure 3.8. QFN-40 Landing Diagram

#### Table 3.6. QFN-40 Landing Diagram Dimensions

Dimension	Min	Max	Dimension	Min	Max
C1	5.80	5.90	X2	4.10	4.20
C2	5.80	5.90	Y1	0.75	0.85
е	0.50	0.50 BSC		4.10	4.20
X1	0.15	0.25			

## Notes:

General

- 1. All dimensions shown are in millimeters (mm) unless otherwise noted.
- 2. Dimension and Tolerancing is per the ANSI Y14.5M-1994 specification.
- 3. This Land Pattern Design is based on the IPC-SM-7351 guidelines.
- 4. All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

#### Solder Mask Design

5. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be  $60 \ \mu m$  minimum, all the way around the pad.

#### Stencil Design

- **6.** A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
- 7. The stencil thickness should be 0.125 mm (5 mils).
- 8. The ratio of stencil aperture to land pad size should be 1:1 for all perimeter pads.
- **9.** A 4x4 array of 0.80 mm square openings on a 1.05 mm pitch should be used for the center ground pad.

#### Card Assembly

- **10.** A No-Clean, Type-3 solder paste is recommended.
- **11.** Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.



## Table 4.4. Digital Supply Current with DC-DC Converter Disabled (Continued)

-40 to +85 °C, 25 MHz system clock unless otherwise specified.

Digital Supply Current—Low Power Idle Mode, All peripheral clocks enabled (PCLKEN = 0x0F) (CPU Inactive, not fetching instructions from flash) $I_{BAT}^{2,6}$ $V_{BAT} = 1.8 - 3.8 V, F = 24.5 MHz$ -       1.5       1.9       mA         (includes precision oscillator current) $V_{BAT} = 1.8 - 3.8 V, F = 20 MHz$ -       1.07       -       mA         (includes precision oscillator current) $V_{BAT} = 1.8 - 3.8 V, F = 10 MHz$ -       270       - $\mu A$ $V_{BAT} = 1.8 - 3.8 V, F = 1 MHz$ -       280       - $\mu A$ (includes external oscillator/GPIO current) $V_{BAT} = 1.8 - 3.8 V, F = 32.768 kHz$ -       232 <sup>5</sup> - $\mu A$ Ibart Frequency Sensitivity <sup>3</sup> $V_{BAT} = 1.8 - 3.8 V, F = 25 °C$ - $47^5$ - $\mu A/MHz$ Digital Supply Current—Low Power Idle Mode, All Peripheral Clocks Disabled (PCLKEN = 0x00)       (CPU Inactive, not fetching instructions from flash)       - $\mu A$ (includes precision oscillator current)       - $\mu A$ - $\mu A$ - $\mu A$ $I_{BAT}^{2,7}$ $V_{BAT} = 1.8 - 3.8 V, F = 20 MHz$ - $487$ - $\mu A$ (includes external oscillator current)       - $\mu A$ - $\mu A$ - $\mu A$	Parameter	Conditions	Min	Тур	Мах	Units		
	Digital Supply Current— Lo	w Power Idle Mode, All peripheral clocks	s enable	ed (PCL	KEN =	0x0F)		
$I_{BAT}^{2,6} \qquad \qquad$	(CPU Inactive, not fetching	instructions from flash)				_		
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	I <sub>RAT</sub> <sup>2, 6</sup>	V <sub>BAT</sub> = 1.8–3.8 V, F = 24.5 MHz		1.5	1.9	mA		
$\frac{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 20 \text{ MHz}}{(includes low power oscillator current)} \qquad 1.07 \qquad \text{mA}}{(includes low power oscillator current)} \qquad 270 \qquad \muA} \\ \frac{V_{BAT} = 3.8 \text{ V}, F = 1 \text{ MHz}}{V_{BAT} = 3.8 \text{ V}, F = 1 \text{ MHz}} \qquad 280 \qquad \muA} \\ \frac{(includes scalar current)}{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 32.768 \text{ KHz}} \qquad 232^5 \qquad \muA} \\ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 32.768 \text{ KHz}}{(includes SmaRTClock oscillator current)} \qquad 232^5 \qquad \muA} \\ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 32.768 \text{ KHz}}{(includes SmaRTClock oscillator current)} \qquad 232^5 \qquad \muA} \\ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 25 \text{ °C}}{(PU \text{ Lactive, not fetching instructions from fash)} \\ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 20 \text{ MHz}}{(includes precision oscillator current)} \qquad 487 \qquad \muA \\ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 20 \text{ MHz}}{(includes precision oscillator current)} \qquad 487 \qquad \muA \\ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 10 \text{ MHz}}{(includes external oscillator current)} \qquad 487 \qquad \muA \\ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 1 \text{ MHz}}{(includes external oscillator current)} \qquad 90 \qquad \muA \\ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 1 \text{ MHz}}{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 25 \text{ °C}} \qquad 11^5 \qquad \muA \\ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 1 \text{ MHz}}{(includes external oscillator current)} \qquad 90 \qquad \muA \\ V_{BAT} = 3.8 \text{ V}, F = 1 \text{ MHz} \qquad 90 \qquad \muA \\ V_{BAT} = 3.8 \text{ V}, F = 25 \text{ °C} \qquad 11^5 \qquad \muA \\ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, T = 25 \text{ °C}}{(115^5 \text{ C})^2 \text{ M}^2 \text{ M}^2 \text{ W}^2 \text{ M}^2 \text{ W}^2 \text$	DAT	(includes precision oscillator current)			L			
$\label{eq:hardenergy} \left\{ \begin{array}{c c c c c c c c c c c c c c c c c c c $		V <sub>BAT</sub> = 1.8–3.8 V, F = 20 MHz		1.07		mA		
$ \frac{V_{BAT} = 1.8 \text{ V}, \text{ F} = 1 \text{ MHz}}{V_{BAT} = 3.8 \text{ V}, \text{ F} = 1 \text{ MHz}} - 270 - \mu \text{A}}{-280 - \mu \text{A}} $ $ \frac{\mu \text{A}}{\mu \text{A}} $ $ \frac{V_{BAT} = 3.8 \text{ V}, \text{ F} = 1 \text{ MHz}}{(\text{includes external oscillator/GPIO current)}} - 232^5 - \mu \text{A} $ $ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, \text{ F} = 32.768 \text{ KHz}}{(\text{includes SmaRTClock oscillator current)}} - 232^5 - \mu \text{A} $ $ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, \text{ F} = 32.768 \text{ KHz}}{(\text{includes SmaRTClock oscillator current)}} - 475 - \mu \text{A}/\text{MHz} $ $ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, \text{ F} = 25 \text{ °C}}{(-1 + 47^5)} - \mu \text{A}/\text{MHz} $ $ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, \text{ F} = 24.5 \text{ MHz}}{(\text{includes precision oscillator current)}} - 487 - \mu \text{A} $ $ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, \text{ F} = 24.5 \text{ MHz}}{(\text{includes precision oscillator current)}} - 487 - \mu \text{A} $ $ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, \text{ F} = 20 \text{ MHz}}{(\text{includes precision oscillator current)}} - 487 - \mu \text{A} $ $ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, \text{ F} = 20 \text{ MHz}}{(\text{includes precision oscillator current)}} - 90 - \mu \text{A} $ $ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, \text{ F} = 1 \text{ MHz}}{(\text{includes external oscillator/GPIO current)}} - 94 - \mu \text{A} $ $ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, \text{ F} = 1 \text{ MHz}}{(\text{includes external oscillator/GPIO current)}} - 484 - \mu \text{A} $ $ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, \text{ F} = 1 \text{ MHz}}{(\text{includes current)}} - 94 - \mu \text{A} $ $ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, \text{ F} = 1 \text{ MHz}}{(\text{includes external oscillator/GPIO current)}} - 84 - \mu \text{A} $ $ \frac{V_{BAT} = 1.8 - 3.8 \text{ V}, \text{ F} = 1 \text{ MHz}}{V_{BAT} = 3.8 \text{ V}} - 84 - \mu \text{A} $ $ \frac{V_{BAT} = 1.8 \text{ V}}{V_{BAT} = 3.8 \text{ V}} - 84 - \mu \text{A} $ $ \frac{V_{BAT} = 1.8 \text{ V}}{V_{BAT} = 3.8 \text{ V}} - 84 - \mu \text{A} $ $ \frac{V_{BAT} = 3.8 \text{ V}}{V_{BAT} = 3.8 \text{ V}} - 84 - \mu \text{A} $ $ \frac{V_{BAT} = 3.8 \text{ V}}{V_{BAT} = 3.8 \text{ V}} - 84 - \mu \text{A} $ $ \frac{V_{BAT} = 3.8 \text{ V}}{V_{BAT} = 3.8 \text{ V}} - 84 - \mu \text{A} $ $ \frac{V_{BAT} = 3.8 \text{ V}}{V_{BAT} = 3.8 \text{ V}} - 84 - \mu \text{A} $ $ \frac{V_{BAT} = 3.8 \text{ V}}{V_{BAT} = 3.8 \text{ V}} - 84 - \mu \text{A} $ $ \frac{V_{BAT} = 3.8 \text{ V}}{V_{BAT} = 3.8 \text{ V} - 84 - \mu \text{A} $ $ V_$		(includes low power oscillator current)			L			
$\frac{V_{BAT} = 3.8 \text{ V}, F = 1 \text{ MHz}}{(\text{includes external oscillator/GPIO current)}} - 280 - \mu^{A}$ $\frac{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 32.768 \text{ kHz}}{(\text{includes SmaRTClock oscillator current)}} - 232^{5} - \mu^{A}$ $\frac{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 32.768 \text{ kHz}}{(\text{includes SmaRTClock oscillator current)}} - 47^{5} - \mu^{A}/\text{MHz}$ Digital Supply Current - Low Power Idle Mode, All Peripheral Clocks Disabled (PCLKEN = 0x00) (CPU Inactive, not fetching instructions from flash) $\frac{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 24.5 \text{ MHz}}{(\text{includes precision oscillator current)}} - 487 - \mu^{A}$ $\frac{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 20 \text{ MHz}}{(\text{includes low power oscillator current)}} - 340 - \mu^{A}$ $\frac{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 20 \text{ MHz}}{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 20 \text{ MHz}} - 90 - \mu^{A}$ $\frac{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 1 \text{ MHz}}{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 1 \text{ MHz}} - 90 - \mu^{A}$ $\frac{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 1 \text{ MHz}}{V_{BAT} = 1.8 - 3.8 \text{ V}, F = 25 \text{ °C}} - 11^{5} - \mu^{A}/\text{MHz}}$ Digital Supply Current—Suspend Mode Digital Supply Current—Suspend Mode Notes: 1. Active Current measure using typical code loop - Digital Supply Current depends upon the particular code being executed. Digital Supply Current depends on the particular code being executed. The values in this table are obtained with the CPU executing a mix of instructions in two loops: din Z R 1, \$ followed by a loop that accesses and power consumption. 2. Includes oscillator supply current. 3. Based on device characterization data; Not production tested. 4. Measured with one-shot enabled. 5. Low-Power Idle mode current measured with CLKMODE = 0x04, PCON = 0x01, and PCLKEN = 0x0F.		V <sub>BAT</sub> = 1.8 V, F = 1 MHz		270		μA		
$\begin{tabular}{ c                                   $		V <sub>BAT</sub> = 3.8 V, F = 1 MHz	—	280		μA		
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Digital Supply Current—Low Power Idle Mode, All Peripheral Clocks Disabled (PCLKEN = 0x00) (CPU Inactive, not fetching instructions from flash)         I <sub>BAT</sub> <sup>2, 7</sup>	I <sub>BAT</sub> Frequency Sensitivity <sup>3</sup>	V <sub>BAT</sub> = 1.8–3.8 V, T = 25 °C		47 <sup>5</sup>	—	µA/MHz		
Identify instructions information $I_{BAT}^{2,7}$ $V_{BAT} = 1.8 - 3.8 V, F = 24.5 MHz$ - $487$ - $\mu A$ $(includes precision oscillator current)$ $V_{BAT} = 1.8 - 3.8 V, F = 20 MHz$ - $340$ - $\mu A$ $(includes low power oscillator current)$ $V_{BAT} = 1.8 - 3.8 V, F = 1 MHz$ - $90$ - $\mu A$ $V_{BAT} = 1.8 - 3.8 V, F = 1 MHz$ - $90$ - $\mu A$ $(includes external oscillator/GPIO current)$ $V_{BAT} = 3.8 V, F = 1 MHz$ - $94$ - $\mu A$ $I_{BAT}$ Frequency Sensitivity <sup>3</sup> $V_{BAT} = 1.8 - 3.8 V, T = 25 °C$ - $11^5$ - $\mu A/MHz$ Digital Supply Current—Suspend ModeDigital Supply Current $V_{BAT} = 1.8 V$ - $77$ - $\mu A$ Notes:1. Active Current measure using typical code loop - Digital Supply Current depends upon the particular code being executed. Digital Supply Current depends on the particular code being executed. The values in this table are obtained with the CPU executing a mix of instructions in two loops: djnz R1, \$, followed by a loop that accesses an SFR, and moves data around using the CPU (between accumulator and b-register). The supply current will vary slightly based on the physical location of this code in flash. As described in the Flash Memory chapter, it is best to align the jump addresses with a flash word address (byte location /4), to minimize flash accesses and power consumption.2. Includes oscillator and regulator supply current.3. Based on device characterization data; Not production tested.4. Measured with one-shot enabled.5. Low-Power Idle mode current measured with CL	Digital Supply Current— Lo	w Power Idle Mode, All Peripheral Clock	s Disab	led (PC	LKEN	= 0x00)		
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$\frac{V_{BAT} = 1.0 - 3.0 \text{ V}, F = 20 \text{ MHz}}{(\text{includes low power oscillator current)}} \qquad $				240				
(Includes low power oscillator current) $V_{BAT} = 1.8 V, F = 1 MHz$ $ 90$ $ \mu A$ $V_{BAT} = 3.8 V, F = 1 MHz$ $ 94$ $ \mu A$ (includes external oscillator/GPIO current) $115$ $ \mu A$ /MHzDigital Supply Current—Suspend ModeDigital Supply Current $V_{BAT} = 1.8 - 3.8 V, T = 25 °C$ $ 11^5$ $ \mu A$ /MHzDigital Supply Current $V_{BAT} = 1.8 V$ $ 77$ $ \mu A$ (Suspend Mode)Notes:1. Active Current measure using typical code loop - Digital Supply Current depends upon the particular code being executed. Digital Supply Current depends on the particular code being executed. The values in this table are obtained with the CPU executing a mix of instructions in two loops: djnz R1, \$, followed by a loop that accesses an SFR, and moves data around using the CPU (between accumulator and b-register). The supply current will vary slightly based on the physical location of this code in flash. As described in the Flash Memory chapter, it is best to align the jump addresses with a flash word address (byte location /4), to minimize flash accesses and power consumption.2. Includes oscillator and regulator supply current.3. Based on device characterization data; Not production tested.4. Measured with one-shot enabled.5. Low-Power Idle mode current measured with CLKMODE = 0x04, PCON = 0x01, and PCLKEN = 0x0F.Current weat accurrent measure with budget 20, 270 MHz OMOS elect. Data acting the purpt with a super the super test of this colspan="2">Dincludes oscillator and regulat		$V_{BAT} = 1.8 - 3.8 \text{ V}, \text{ F} = 20 \text{ MHz}$		340		μΑ		
$V_{BAT} = 1.8 V, F = 1 MHZ$ $ 90$ $ \mu A$ $V_{BAT} = 3.8 V, F = 1 MHZ$ $ 94$ $ \mu A$ (includes external oscillator/GPIO current) $1_{BAT}$ $ 94$ $ \mu A$ IBAT Frequency Sensitivity <sup>3</sup> $V_{BAT} = 1.8-3.8 V, T = 25 °C$ $ 11^5$ $ \mu A/MHZ$ Digital Supply Current—Suspend ModeDigital Supply Current (Suspend Mode) $V_{BAT} = 1.8 V$ $ 77$ $ \mu A$ Notes:1. Active Current measure using typical code loop - Digital Supply Current depends upon the particular code being executed. Digital Supply Current depends on the particular code being executed. The values in this table are obtained with the CPU executing a mix of instructions in two loops: djnz R1, \$, followed by a loop that accesses an SFR, and moves data around using the CPU (between accumulator and b-register). The supply current will vary slightly based on the physical location of this code in flash. As described in the Flash Memory chapter, it is best to align the jump addresses with a flash word address (byte location /4), to minimize flash accesses and power consumption.2. Includes oscillator and regulator supply current.3. Based on device characterization data; Not production tested.4. Measured with one-shot enabled.5. Low-Power Idle mode current measured with CLKMODE = 0x04, PCON = 0x01, and PCLKEN = 0x0F.2. Where Current be and the sufficience with current measured with CLKMODE = 0x04, PCON = 0x01, and PCLKEN = 0x0F.								
VBAT = 3.0 V, F = 1 MI12       34       μrx         (includes external oscillator/GPIO current)       1       1       μrx         IBAT Frequency Sensitivity <sup>3</sup> VBAT = 1.8–3.8 V, T = 25 °C       11 <sup>5</sup> μA/MHz         Digital Supply Current—Suspend Mode       VBAT = 1.8 V       77       μA         Digital Supply Current       VBAT = 1.8 V       77       μA         (Suspend Mode)       VBAT = 3.8 V       84       -         Notes:       1.       Active Current measure using typical code loop - Digital Supply Current depends upon the particular code being executed. Digital Supply Current depends on the particular code being executed. The values in this table are obtained with the CPU executing a mix of instructions in two loops: djnz R1, \$, followed by a loop that accesses an SFR, and moves data around using the CPU (between accumulator and b-register). The supply current will vary slightly based on the physical location of this code in flash. As described in the Flash Memory chapter, it is best to align the jump addresses with a flash word address (byte location /4), to minimize flash accesses and power consumption.         2.       Includes oscillator and regulator supply current.         3.       Based on device characterization data; Not production tested.         4.       Measured with one-shot enabled.         5.       Low-Power Idle mode current measured with CLKMODE = 0x04, PCON = 0x01, and PCLKEN = 0x0F.		$V_{BAT} = 1.8 V, \Gamma = 1.10 \Pi Z$		90 04		μΑ		
Image: transmission of the content y       μA/MHz         I <sub>BAT</sub> Frequency Sensitivity <sup>3</sup> V <sub>BAT</sub> = 1.8–3.8 V, T = 25 °C       −       11 <sup>5</sup> µA/MHz         Digital Supply Current—Suspend Mode       V       −       77       −       µA         (Suspend Mode)       V <sub>BAT</sub> = 3.8 V       −       84       −          Notes:       1.       Active Current measure using typical code loop - Digital Supply Current depends upon the particular code being executed. Digital Supply Current depends on the particular code being executed. The values in this table are obtained with the CPU executing a mix of instructions in two loops: djnz R1, \$, followed by a loop that accesses an SFR, and moves data around using the CPU (between accumulator and b-register). The supply current will vary slightly based on the physical location of this code in flash. As described in the Flash Memory chapter, it is best to align the jump addresses with a flash word address (byte location /4), to minimize flash accesses and power consumption.         2.       Includes oscillator and regulator supply current.         3.       Based on device characterization data; Not production tested.         4.       Measured with one-shot enabled.         5.       Low-Power Idle mode current measured with CLKMODE = 0x04, PCON = 0x01, and PCLKEN = 0x0F.		$v_{BAT} = 3.0 \text{ v}, \Gamma = 1 \text{ winz}$		34		μΥ		
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Digital Supply Current—Suspend Mode         Digital Supply Current       V <sub>BAT</sub> = 1.8 V       -       77       -       μA         (Suspend Mode)       V <sub>BAT</sub> = 3.8 V       -       84       -         Notes:       1. Active Current measure using typical code loop - Digital Supply Current depends upon the particular code being executed. Digital Supply Current depends on the particular code being executed. The values in this table are obtained with the CPU executing a mix of instructions in two loops: djnz R1, \$, followed by a loop that accesses an SFR, and moves data around using the CPU (between accumulator and b-register). The supply current will vary slightly based on the physical location of this code in flash. As described in the Flash Memory chapter, it is best to align the jump addresses with a flash word address (byte location /4), to minimize flash accesses and power consumption.         2. Includes oscillator and regulator supply current.         3. Based on device characterization data; Not production tested.         4. Measured with one-shot enabled.         5. Low-Power Idle mode current measured with CLKMODE = 0x04, PCON = 0x01, and PCLKEN = 0x0F.	IBAT Frequency Sensitivity	V <sub>BAT</sub> = 1.8–3.8 V, I = 25 °C		11 <sup>-</sup>		μΑνινιπΖ		
Digital Supply Current       V <sub>BAT</sub> = 1.8 V        77        μA         (Suspend Mode)       V <sub>BAT</sub> = 3.8 V        84        μA         Notes:        84        μA         1. Active Current measure using typical code loop - Digital Supply Current depends upon the particular code being executed. Digital Supply Current depends on the particular code being executed. The values in this table are obtained with the CPU executing a mix of instructions in two loops: djnz R1, \$, followed by a loop that accesses an SFR, and moves data around using the CPU (between accumulator and b-register). The supply current will vary slightly based on the physical location of this code in flash. As described in the Flash Memory chapter, it is best to align the jump addresses with a flash word address (byte location /4), to minimize flash accesses and power consumption.       2         2. Includes oscillator and regulator supply current.       3.       Based on device characterization data; Not production tested.         4. Measured with one-shot enabled.       5.       Low-Power Idle mode current measured with CLKMODE = 0x04, PCON = 0x01, and PCLKEN = 0x0F.	Digital Supply Current—Sus	spend Mode						
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<ol> <li>Active Current measure using typical code loop - Digital Supply Current depends upon the particular code being executed. Digital Supply Current depends on the particular code being executed. The values in this table are obtained with the CPU executing a mix of instructions in two loops: djnz R1, \$, followed by a loop that accesses an SFR, and moves data around using the CPU (between accumulator and b-register). The supply current will vary slightly based on the physical location of this code in flash. As described in the Flash Memory chapter, it is best to align the jump addresses with a flash word address (byte location /4), to minimize flash accesses and power consumption.</li> <li>Includes oscillator and regulator supply current.</li> <li>Based on device characterization data; Not production tested.</li> <li>Measured with one-shot enabled.</li> <li>Low-Power Idle mode current measured with CLKMODE = 0x04, PCON = 0x01, and PCLKEN = 0x0F.</li> </ol>	Notes:							
<ul> <li>being executed. Digital Supply Current depends on the particular code being executed. The values in this table are obtained with the CPU executing a mix of instructions in two loops: djnz R1, \$, followed by a loop that accesses an SFR, and moves data around using the CPU (between accumulator and b-register). The supply current will vary slightly based on the physical location of this code in flash. As described in the Flash Memory chapter, it is best to align the jump addresses with a flash word address (byte location /4), to minimize flash accesses and power consumption.</li> <li>Includes oscillator and regulator supply current.</li> <li>Based on device characterization data; Not production tested.</li> <li>Measured with one-shot enabled.</li> <li>Low-Power Idle mode current measured with CLKMODE = 0x04, PCON = 0x01, and PCLKEN = 0x0F.</li> </ul>	1. Active Current measure u	sing typical code loop - Digital Supply Current de	epends ι	pon the	particula	ar code		
<ul> <li>table are obtained with the OFO executing a mix of instructions in two hopps, directly of hopps, di</li></ul>	being executed. Digital St table are obtained with th	upply Current depends on the particular code be	ing exec	uted. In R1 \$ fol	e values	in this		
<ul> <li>supply current will vary slightly based on the physical location of this code in flash. As described in the Flash Memory chapter, it is best to align the jump addresses with a flash word address (byte location /4), to minimize flash accesses and power consumption.</li> <li>Includes oscillator and regulator supply current.</li> <li>Based on device characterization data; Not production tested.</li> <li>Measured with one-shot enabled.</li> <li>Low-Power Idle mode current measured with CLKMODE = 0x04, PCON = 0x01, and PCLKEN = 0x0F.</li> </ul>	that accesses an SFR, ar	id moves data around using the CPU (between a	accumula	ator and	b-registe	er). The		
<ul> <li>Memory chapter, it is best to align the jump addresses with a flash word address (byte location /4), to minimize flash accesses and power consumption.</li> <li>Includes oscillator and regulator supply current.</li> <li>Based on device characterization data; Not production tested.</li> <li>Measured with one-shot enabled.</li> <li>Low-Power Idle mode current measured with CLKMODE = 0x04, PCON = 0x01, and PCLKEN = 0x0F.</li> </ul>	supply current will vary sli	ightly based on the physical location of this code	in flash.	As desc	ribed in	the Flash		
<ul> <li>minimize flash accesses and power consumption.</li> <li>Includes oscillator and regulator supply current.</li> <li>Based on device characterization data; Not production tested.</li> <li>Measured with one-shot enabled.</li> <li>Low-Power Idle mode current measured with CLKMODE = 0x04, PCON = 0x01, and PCLKEN = 0x0F.</li> <li>Indexe Disclosely estimates with external 22,700 kHz CMOS closely. Deep net include extertal bias current.</li> </ul>	Memory chapter, it is best	Memory chapter, it is best to align the jump addresses with a flash word address (byte location /4), to						
<ol> <li>Includes oscillator and regulator supply current.</li> <li>Based on device characterization data; Not production tested.</li> <li>Measured with one-shot enabled.</li> <li>Low-Power Idle mode current measured with CLKMODE = 0x04, PCON = 0x01, and PCLKEN = 0x0F.</li> <li>Union Operational Content of the endotre of the endo</li></ol>	minimize flash accesses a	minimize flash accesses and power consumption.						
<ol> <li>Based on device characterization data; Not production tested.</li> <li>Measured with one-shot enabled.</li> <li>Low-Power Idle mode current measured with CLKMODE = 0x04, PCON = 0x01, and PCLKEN = 0x0F.</li> <li>Universe DTCleak esiliates with external 22 ZC2 kHz CMOS cleak. Data not include crutel bias current.</li> </ol>	2. Includes oscillator and reg	2. Includes oscillator and regulator supply current.						
<ol> <li>Measured with one-shot enabled.</li> <li>Low-Power Idle mode current measured with CLKMODE = 0x04, PCON = 0x01, and PCLKEN = 0x0F.</li> <li>Using Constraints with enternal 22 Z02 kHz CMOS clock. Does not include crutel bios current.</li> </ol>	3. Based on device character	rization data; Not production tested.						
5. LOW-POWER rate mode current measured with CLKMODE = 0x04, PCON = 0x01, and PCLKEN = 0x07.	4. Measured with one-shot e		0.01			- <b>^</b> F		
	5. Low-Power late mode cur	Tent measured with CLKWODE = 0x04, POON =	= UXU1, a	.na PULr		(UF.		

7. Low-Power Idle mode current measured with CLKMODE = 0x04, PCON = 0x01, and PCLKEN = 0x00.



# SFR Definition 5.4. ADC0PWR: ADC0 Burst Mode Power-Up Time

Bit	7	6	5	4	3	2	1	0
Name	AD0LPM				AD0PWR[3:0]			
Туре	R/W	R	R	R	R/W			
Reset	0	0	0	0	1	1	1	1

#### SFR Page = 0xF; SFR Address = 0xBA

Bit	Name	Function
7	AD0LPM	ADC0 Low Power Mode Enable.
		Enables Low Power Mode Operation.
		0: Low Power Mode disabled.
		1: Low Power Mode enabled.
6:4	Unused	Read = 0000b; Write = Don't Care.
3:0	AD0PWR[3:0]	ADC0 Burst Mode Power-Up Time.
		Sets the time delay required for ADC0 to power up from a low power state. For BURSTEN = 0:
		ADC0 power state controlled by AD0EN.
		For BURSTEN = 1 and AD0EN = 1:
		ADC0 remains enabled and does not enter a low power state after
		all conversions are complete.
		Conversions can begin immediately following the stan-of-conversion signal. For $PUPSTEN = 1$ and $ADOEN = 0$ :
		FOI BORSTEIN = T allo ADOEIN = 0. ADCO enters a low power state after all conversions are complete
		Conversions can begin a programmed delay after the start-of-conversion signal.
		The ADC0 Burst Mode Power-Up time is programmed according to the following equation:
		$ADOPWR = \frac{Tstartup}{400ns} - 1$
		or
		Tstartup = (AD0PWR + 1)400ns
		<b>Note:</b> Setting AD0PWR to 0x04 provides a typical tracking time of 2 us for the first sample taken after the start of conversion.



#### 10.5.1. Internal XRAM Only

When bits EMI0CF[3:2] are set to 00, all MOVX instructions will target the internal XRAM space on the device. Memory accesses to addresses beyond the populated space will wrap on 8 kB boundaries. As an example, the addresses 0x2000 and 0x4000 both evaluate to address 0x0000 in on-chip XRAM space.

- 8-bit MOVX operations use the contents of EMI0CN to determine the high-byte of the effective address and R0 or R1 to determine the low-byte of the effective address.
- 16-bit MOVX operations use the contents of the 16-bit DPTR to determine the effective address.

#### 10.5.2. Split Mode without Bank Select

When bit EMI0CF.[3:2] are set to 01, the XRAM memory map is split into two areas, on-chip space and offchip space.

- Effective addresses below the internal XRAM size boundary will access on-chip XRAM space.
- Effective addresses above the internal XRAM size boundary will access off-chip space.
- 8-bit MOVX operations use the contents of EMI0CN to determine whether the memory access is onchip or off-chip. However, in the "No Bank Select" mode, an 8-bit MOVX operation will not drive the upper 8-bits A[15:8] of the Address Bus during an off-chip access. This allows the user to manipulate the upper address bits at will by setting the Port state directly via the port latches. This behavior is in contrast with "Split Mode with Bank Select" described below. The lower 8-bits of the Address Bus A[7:0] are driven, determined by R0 or R1.
- 16-bit MOVX operations use the contents of DPTR to determine whether the memory access is on-chip or off-chip, and unlike 8-bit MOVX operations, the full 16-bits of the Address Bus A[15:0] are driven during the off-chip transaction.

#### 10.5.3. Split Mode with Bank Select

When EMI0CF[3:2] are set to 10, the XRAM memory map is split into two areas, on-chip space and offchip space.

- Effective addresses below the internal XRAM size boundary will access on-chip XRAM space.
- Effective addresses above the internal XRAM size boundary will access off-chip space.
- 8-bit MOVX operations use the contents of EMI0CN to determine whether the memory access is onchip or off-chip. The upper 8-bits of the Address Bus A[15:8] are determined by EMI0CN, and the lower 8-bits of the Address Bus A[7:0] are determined by R0 or R1. All 16-bits of the Address Bus A[15:0] are driven in "Bank Select" mode.
- 16-bit MOVX operations use the contents of DPTR to determine whether the memory access is on-chip or off-chip, and the full 16-bits of the Address Bus A[15:0] are driven during the off-chip transaction.

#### 10.5.4. External Only

When EMI0CF[3:2] are set to 11, all MOVX operations are directed to off-chip space. On-chip XRAM is not visible to the CPU. This mode is useful for accessing off-chip memory located between 0x0000 and the internal XRAM size boundary.

- 8-bit MOVX operations ignore the contents of EMI0CN. The upper Address bits A[15:8] are not driven (identical behavior to an off-chip access in "Split Mode without Bank Select" described above). This allows the user to manipulate the upper address bits at will by setting the Port state directly. The lower 8-bits of the effective address A[7:0] are determined by the contents of R0 or R1.
- 16-bit MOVX operations use the contents of DPTR to determine the effective address A[15:0]. The full 16-bits of the Address Bus A[15:0] are driven during the off-chip transaction.



#### 10.6.1.3. 8-bit MOVX with Bank Select: EMI0CF[4:2] = 110



Figure 10.6. Non-multiplexed 8-bit MOVX with Bank Select Timing



- " Disable the DMA by writing 0x00 to DMAOEN
- " Increment counter and repeat all steps for additional blocks
- 14.6.6.1. CTR Encryption using SFRs
- " First Configure AES Module for CTR Block Cipher Mode Encryption
  - z Reset AES module by writing 0x00 to AESOBCFG.
  - z Configure the AES Module data flow for XOR onpostutata by writing Oxto2the AESODCFG sfr.
  - z Write key size to bits 1 and 0 of the AESOBCFG.
  - z Configure the AES core fœncryption by setting bit 2 of AESOBCFG.
  - z Enable the AES core by setting bit 3 of AESOBCFG.
  - Repeat alternating write sequence 16 times
  - z Write plaintext byte to AESOBIN.
  - z Write counter by to AESOXIN
  - z Write encryption key byte to AESOKIN.
- " Write remaining encryption key bytes to AESOKIN for 192-bit and 256-bit decryption only.
- " Wait on AES done interrupt or poll bit 5 of AESOBCFG.
- " Read 16 encrypted bytes from the AESOYOUT sfr.

If encrypting multiple blockiscrement the counter and eat this process. It inst necessary reconfigure the AES module for each block.

# 31. Enhanced Serial Peripheral Interface with DMA Support (SPI1)

The Enhanced Serial Peripheral Interface (SPI1) piddes access to a flexible, full-duplex synchronous serial bus. SPI1 can operate as a snaer or slave device in both 3 ewin 4-wire modes, and supports multiple masters and slaves on a single SPI bus. There-select (NSS) signal can be configured as an input to select SPI1 in slave mode, or to disable to disable to a multi-master environment, avoiding contention on the SPI bus when more to the master attempts simultaneous data transfers. NSS can also be configured as a chip-select outiput master mode, or disabled for 3-wire operation. Additional general purpose port I/O pins can be uses elect multiple slave evices in master mode.





# SFR Definition 19.5. PMU0FL: Power Management Unit Flag<sup>1,2</sup>

Bit	7	6	5	4	3	2	1	0
Name						BATMWK	Reserved	PC0WK
Туре	R	R	R	R	R	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	Varies

SFR Page = 0x0; SFR Address = 0xB6

Bit	Name	Description	Write	Read
7:3	Unused	Unused	Don't Care.	000000
2	BATMWK	VBAT Monitor (inside LCD Logic) Wake-up Source Enable and Flag	0: Disable wake-up on VBAT Monitor event. 1: Enable wake-up on CS0 event.	Set to 1 if VBAT Monitor event caused the last wake-up.
1	Reserved	Reserved	Must write 0.	Always reads 0.
0	CS0WK	Pulse Counter Wake-up Source Enable and Flag	0: Disable wake-up on PC0 event. 1: Enable wake-up on PC0 event.	Set to 1 if PC0 event caused the last wake-up.

Notes:

1. The Low Power Internal Oscillator cannot be disabled and the MCU cannot be placed in suspend or sleep mode if any wake-up flags are set to 1. Software should clear all wake-up sources after each reset and after each wake-up from Suspend or Sleep Modes.

2. PMU0 requires two system clocks to update the wake-up source flags after waking from suspend mode. The wake-up source flags will read 0 during the first two system clocks following the wake from suspend mode.



## SFR Definition 22.2. RSTSRC: Reset Source

Bit	7	6	5	4	3	2	1	0
Name	RTC0RE	FERROR	C0RSEF	SWRSF	WDTRSF	MCDRSF	PORSF	PINRSF
Туре	R/W	R	R/W	R/W	R	R/W	R/W	R
Reset	Varies							

SFR Page = 0x0; SFR Address = 0xEF.

Bit	Name	Description	Write	Read
7	RTC0RE	SmaRTClock Reset Enable and Flag	0: Disable SmaRTClock as a reset source. 1: Enable SmaRTClock as a reset source.	Set to 1 if SmaRTClock alarm or oscillator fail caused the last reset.
6	FERROR	Flash Error Reset Flag.	N/A	Set to 1 if Flash read/write/erase error caused the last reset.
5	CORSEF	Comparator0 Reset Enable and Flag.	0: Disable Comparator0 as a reset source. 1: Enable Comparator0 as a reset source.	Set to 1 if Comparator0 caused the last reset.
4	SWRSF	Software Reset Force and Flag.	Writing a 1 forces a sys- tem reset.	Set to 1 if last reset was caused by a write to SWRSF.
3	WDTRSF	Watchdog Timer Reset Flag.	N/A	Set to 1 if Watchdog Timer overflow caused the last reset.
2	MCDRSF	Missing Clock Detector (MCD) Enable and Flag.	0: Disable the MCD. 1: Enable the MCD. The MCD triggers a reset if a missing clock condition is detected.	Set to 1 if Missing Clock Detector timeout caused the last reset.
1	PORSF	Power-On / Power-Fail Reset Flag, and Power-Fail Reset Enable.	0: Disable the VDD Supply Monitor as a reset source. 1: Enable the VDD Supply Monitor as a reset source. <sup>3</sup>	Set to 1 anytime a power- on or V <sub>DD</sub> monitor reset occurs. <sup>2</sup>
0 Notor	PINRSF	HW Pin Reset Flag.	N/A	Set to 1 if RST pin caused the last reset.
Notes	5:			

1. It is safe to use read-modify-write operations (ORL, ANL, etc.) to enable or disable specific interrupt sources.

2. If PORSF read back 1, the value read from all other bits in this register are indeterminate.

3. Writing a 1 to PORSF before the VDD Supply Monitor is stabilized may generate a system reset.



# 25. Low-Power Pulse Counter

The C8051F960x family of microcontrollers contains a low-power Pulse Counter module with advanced features, such as ultra low power input comparators, a wide range of pull up values with a self calibration engine, asymmetrical integrators for low pass filtering and switch debounce, single, dual, and quadrature modes of operation, two 24-bit counters, threshold comparators, and a variety of interrupt and sleep wake up capabilities. This combination of features provides water, gas, and heat metering system designers with an optimal tool for saving power while collecting meter usage data.



Figure 25.1. Pulse Counter Block Diagram

The low-power Pulse Counter is a low-power sleep-mode peripheral designed primarily to work meters using reed switches, including water and gas meters. The Pulse Counter is very flexible and can count pulses from many different types of sources.

The Pulse Counter operates in sleep mode to enable ultra-low power metering systems. The MCU does not have to wake up on every edge or transition and can remain in sleep mode while the Pulse Counter counts pulses for an extended period of time. The Pulse Counter includes two 24-bit counters. These counters can count up to 16,777,215 (2<sup>24</sup>-1) transitions in sleep mode before overflowing. The Pulse Counter can wake up the MCU when one of the counters overflows. The Pulse Counter also has two 24-bit comparators. The comparators have the ability to wake up the MCU when the one of the counters reaches a predetermined threshold.

The Pulse Counter uses the RTC clock for sampling, de-bouncing, and managing the low-power pull-up resistors. The RTC must be enabled when counting pulses. The RTC alarms can wake up the MCU periodically to read the pulse counters, instead of using the Pulse Counter comparators. For example, the RTC can wake up the MCU every five minutes. The MCU can then read the Pulse Counter and transmit the information using the UART or a wireless transceiver.



## 25.1. Counting Modes

The Pulse Counter supports three different counting modes: single counter mode, dual counter mode, and quadrature counter mode. Figure 25.2 illustrates the three counter modes.



The single counter mode uses only one Pulse Counter pin PC0 (P1.0) to count pulses from a single input channel. This mode uses only counter 0 and comparator. (Counter 1 and comparator 1 are not used.) The single counter mode supports only one meter-encoder with a single-channel output. A single-channel encoder is an effective solution when the metered fluid flows only in one direction. A single-channel encoder does not provide any direction information and does not support bidirectional fluid metering.

The dual counter mode supports two independent single-channel meters. Each meter has its own independent counter and comparator. Some of the global configuration settings apply to both channels, such as pull-up current, sampling rate, and debounce time. The dual mode may also be used for a redundant count using a two-channel non-quadrature encoder.

Quadrature counter mode supports a single two-channel quadrature meter encoder. The quadrature counter mode supports bidirectional encoders and applications with bidirectional fluid flow. In quadrature counter mode, clock-wise counts will increment counter 0, while counter clock-wise counts will increment counter 1. Subtracting counter 1 from counter 0 will yield the net position. If the normal fluid flow is clock-



enable signal. The enable signal enables the pull-up resistor when high and disables when low. PC0 is the line to the reed switch. On the right side of PC0 waveform, the line voltage is decreasing towards ground when the pull-up resistors are disabled. Beneath the charging waveform, the arrows represent the sample points. The pulse counter samples the PC0 voltage once the charging completes. The sensed ones and zeros are the sampled data. Finally the integrator waveform illustrates the output of the digital integrator. The integrator is set to 4 initially and counts to down to 0 before toggling the output low. Once the integrator reaches the low state, it needs to count up to 4 before toggling its output to the high state. The debounce logic filters out switch bounce or noise that appears for a short duration.



Figure 25.4. Debounce Timing

## 25.7. Reset Behavior

Unlike most MCU peripherals, an MCU reset does not completely reset the Pulse Counter. This includes a power on reset and all other reset sources. An MCU reset does not clear the counter values. The Pulse Counter SFRs do not reset to a default value upon reset. The 24-bit counter values are persistent unless cleared manually by writing to the PC0MD SFR. Note that if the VBAT voltage ever drops below the minimum operating voltage, this may compromise contents of the counters.

The PC0MD register should normally be written only once after reset. The PC0MD SFR is the master mode register. This register sets the counter mode and sample rate. Writing to the PC0MD SFR also resets the other PC0xxx SFRs.

Note that the RTC clock will reset on an MCU reset, so counting cannot resume until the RTC clock has been re-started.

Firmware should read the reset sources SFR RSTSRC to determine the source of the last reset and initialize the Pulse Counter accordingly.

When the pulse counter resets, it takes some time (typically two RTC clock cycles) to synchronize between internal clock domains. The counters do not increment during this synchronization time.

## 25.8. Wake up and Interrupt Sources

The Pulse Counter has multiple interrupt and wake-up source conditions. To enable an interrupt, enable the source in the PC0INT0/1 SFRs and enable the Pulse Counter interrupt using bit 4 of the EIE2 bit register. The Pulse Counter interrupt service routine should read the interrupt flags in PC0INT0/1 to determine the source of the interrupt and clear the interrupt flags.



# SFR Definition 26.5. LCD0MSCF: LCD0 Master Configuration

Bit	7	6	5	4	3	2	1	0
Name							DCENSLP	CHPBYP
Туре	R/W	R/W						
Reset	1	1	1	1	1	1	1	0

#### SFR Page = 0x2; SFR Address = 0xAC

Bit	Name	Function
7:2	Reserved	Read = 111111b. Must write 111111b.
1	DCENSLP	DCDC Converter Enable in Sleep Mode
		0: DCDC is disabled in Sleep Mode.
		1: DCDC is enabled in Sleep Mode.
0	CHPBYP	LCD0 Charge Pump Bypass
		This bit should be set to 1b in Contrast Control Mode 1 and Mode 2.
		0: LCD0 Charge Pump is not bypassed.
		1: LCD0 Charge Pump is bypassed.

## SFR Definition 26.6. LCD0PWR: LCD0 Power

Bit	7	6	5	4	3	2	1	0
Name					MODE			
Туре	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Reset	0	0	0	0	1	0	0	1

#### SFR Page = 0x2; SFR Address = 0xA4

Bit	Name	Function
7:4	Unused	Read = 0000b. Write = don't care.
3	MODE	LCD0 Contrast Control Mode Selection.
		0: LCD0 Contrast Control Mode 1 or Mode 4 is selected.
		1: LCD0 Contrast Control Mode 2 or Mode 3 is selected.
2:0	Reserved	Read = 001b. Must write 001b.



# SFR Definition 27.36. P6MDIN: Port6 Input Mode

Bit	7	6	5	4	3	2	1	0
Name	P6MDIN[7:0]							
Туре	R/W							
Reset	1	1	1	1	1	1	1	1

SFR Page = 0xF; SFR Address = 0xF4

Bit	Name	Function
7:0	P6MDIN[3:0]	Analog Configuration Bits for P6.7–P6.0 (respectively).
		<ul><li>Port pins configured for analog mode have their weak pullup and digital receiver disabled. The digital driver is not explicitly disabled.</li><li>0: Corresponding P6.n pin is configured for analog mode.</li><li>1: Corresponding P6.n pin is not configured for analog mode.</li></ul>

# SFR Definition 27.37. P6MDOUT: Port6 Output Mode

Bit	7	6	5	4	3	2	1	0
Name	P6MDOUT[7:0]							
Туре	R/W							
Reset	0	0	0	0	0	0	0	0

#### SFR Page = 0xF; SFR Address = 0xFB

Bit	Name	Function
7:0	P6MDOUT[7:0]	Output Configuration Bits for P6.7–P6.0 (respectively).
		These bits control the digital driver even when the corresponding bit in register P6MDIN is logic 0. 0: Corresponding P6.n Output is open-drain. 1: Corresponding P6.n Output is push-pull.



# SFR Definition 27.38. P6DRV: Port6 Drive Strength

Bit	7	6	5	4	3	2	1	0
Name	P6DRV[7:0]							
Туре				R/	W			
Reset	0	0	0	0	0	0	0	0

SFR Page = 0xF; SFR Address = 0xAA

Bit	Name	Function
7:0	P6DRV[7:0]	Drive Strength Configuration Bits for P6.7–P6.0 (respectively).
		Configures digital I/O Port cells to high or low output drive strength. 0: Corresponding P6.n Output has low output drive strength. 1: Corresponding P6.n Output has high output drive strength.

# SFR Definition 27.39. P7: Port7

Bit	7	6	5	4	3	2	1	0
Name								P7.0
Туре								R/W
Reset	1	1	1	1	1	1	1	1

SFR Page = 0xF; SFR Address = 0xDC

Bit	Name	Description	Read	Write				
7:1	Unused	Read = 0000000b; Write = Don't Care.						
0	P7.0	<b>Port 7 Data.</b> Sets the Port latch logic value or reads the Port pin logic state in Port cells con- figured for digital I/O.	0: Set output latch to logic LOW. 1: Set output latch to logic HIGH.	0: P7.0 Port pin is logic LOW. 1: P7.0 Port pin is logic HIGH.				



# SFR Definition 28.2. SMB0CN: SMBus Control

Bit	7	6	5	4	3	2	1	0
Name	MASTER	TXMODE	STA	STO	ACKRQ	ARBLOST	ACK	SI
Туре	R	R	R/W	R/W	R	R	R/W	R/W
Reset	0	0	0	0	0	0	0	0

SFR Page = All Pages; SFR Address = 0xC0; Bit-Addressable

Bit	Name	Description	Read	Write
7	MASTER	SMBus Master/Slave Indicator. This read-only bit indicates when the SMBus is operating as a master.	0: SMBus operating in slave mode. 1: SMBus operating in master mode.	N/A
6	TXMODE	SMBus Transmit Mode Indicator. This read-only bit indicates when the SMBus is operating as a transmitter.	0: SMBus in Receiver Mode. 1: SMBus in Transmitter Mode.	N/A
5	STA	SMBus Start Flag.	0: No Start or repeated Start detected. 1: Start or repeated Start detected.	0: No Start generated. 1: When Configured as a Master, initiates a START or repeated START.
4	STO	SMBus Stop Flag.	0: No Stop condition detected. 1: Stop condition detected (if in Slave Mode) or pend- ing (if in Master Mode).	0: No STOP condition is transmitted. 1: When configured as a Master, causes a STOP condition to be transmit- ted after the next ACK cycle. Cleared by Hardware.
3	ACKRQ	SMBus Acknowledge Request.	0: No Ack requested 1: ACK requested	N/A
2	ARBLOST	SMBus Arbitration Lost Indicator.	0: No arbitration error. 1: Arbitration Lost	N/A
1	ACK	SMBus Acknowledge.	0: NACK received. 1: ACK received.	0: Send NACK 1: Send ACK
0	SI	SMBus Interrupt Flag. This bit is set by hardware under the conditions listed in Table 15.3. SI must be cleared by software. While SI is set, SCL is held low and the SMBus is stalled.	0: No interrupt pending 1: Interrupt Pending	<ul><li>0: Clear interrupt, and initiate next state machine event.</li><li>1: Force interrupt.</li></ul>



# **CONTACT INFORMATION**

#### Silicon Laboratories Inc.

400 West Cesar Chavez Austin, TX 78701

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